Gas Discharge Tubes SG Series

SG Series





Agency Approvals

Agency	Agency File Number
<i>71</i>	E128662

2 Electrode GDT Graphical Symbol



Additional Information







Samples

Description

Littelfuse SG series GDT offers high surge ratings in a miniature package. It's designed for surface mounting on PCB with small size 4.5x3.2x2.7mm. Low insertion loss is perfectly suited to broadband equipment applications. The capacitance does not vary with voltage, and will not cause operational problems with ADSL2+, where capacitance variation across Tip and Ring is undesirable. These devices are extremely robust and are able to divert a 1000A pulse without destruction.

Features

- RoHS compliant and Lead-free
- GHz working frequency
- Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 1-2KA surge capability tested with 8/20µS pulse as defined by IEC 61000-4-5
- Ultra small devices offered in a variety of mounting lead forms
- Non-Radioactive
- Low capacitance (<1pF)
- Voltage Ranges 75V to 600V
- UL Recongized
- Conforms to ITU-T K12, IEC 61000-4-5
- Square Outline

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection

- Broadband equipment
- ADSL equipment, including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- General telecom equipment

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Electrical Characteristics

	Device Specifications (at 25°C)					Life Ratings												
Part Number	i	Breakc in Volt 9100V	S	Impulse Breakdown in Volts (@100V/μs)	Impulse Breakdown In Volts (@1 Kv/	Insulation Resistance	Capaci- tance (@1MHz)	Arc Voltage (@1A)	Glow to Arc Transition Current	Glow Voltage		Impulse Discharge Current (x10	Nominal Impulse Discharge Current (10/1000µs					
	Min.	Тур.	Max.	Max.	µsec)	Min.	Max.				@50Hz)	@8/20μs)	100 cycles)					
SG75	52	75	98	500	650													
SG90	63	90	117	500	600	>1GΩ (at 50VDC)					2 A	2kA						
SG150	105	150	195	500	600	>1GΩ (at 100VDC) >1GΩ (at 50VDC) >1GΩ (at 50VDC)	(at 50 v DC)		~10 V	~1.0 A	~60 V							
SG200+	140	200	260	550	700		<1 pf		1.071		2.5 A							
SG230	172	230	288	650	800				2 A									
SG300	225	300	375	700	850								~12 V	~0.5 A	~90 V	ZA		
SG300Q	210	300	390	580	650						~2	~20 V	~0.8 A	~140 V	NA*		40.4	
SG350	263	350	437	750	900				0.8 pf ~12 V ~0.5 A		~90 V	2 A		10 A				
SG350Q	263	350	437	600	700			<0.8 pf		~140 V	NA*	1kA						
SG400	300	400	500	800	950					~90 V	2 A							
SG420	315	420	525	800	1000		<1 pf		~10 V		~60 V	2 A						
SG420Q	315	420	525	650	750			<1 pf	~20 V	<1.0 A		NA*						
SG450Q	370	450	500	680	750		100	~20 V		~140 V	1 A							
SG500Q	400	500	600	950	1050			<0.5 pf	~16 V	~0.1 A	~ 140 V	2 A						
SG600Q	450	600	750	1100	1200		<1 pf	~20 V	<0.5 A	ZA								

^{*} Specification is not applicable for quick response (SGxxx \mathbf{Q}) version of product

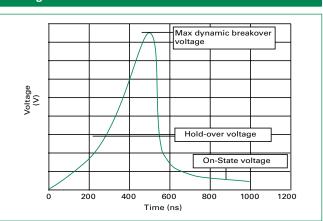
Product Characteristics

Materials	Device Tin Plated 17.5±12.5 Microns Construction Ceramic Insulator.		
Storage and Operational Temperature	-40 to +90 °C		

Typical Insertion Loss

@ 1.0 GHz = 0.01 dB	
@ 1.4GHz = 0.1 dB	
@ 1.8 GHz = 0.53 dB	
@ 2.1 GHz = 0.81 dB	
@ 2.45 GHz= 1 dB	
@ 2.8 GHz = 1.2 dB	
@ 3.1 GHz = 1.5 dB	
@ 3.5 GHz = 2.1 dB	
@ 2.45 GHz= 1 dB @ 2.8 GHz = 1.2 dB @ 3.1 GHz = 1.5 dB	

Voltage vs. Time Characteristic

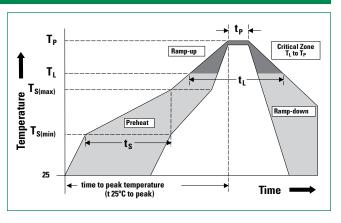


⁺ Not UL Recognized



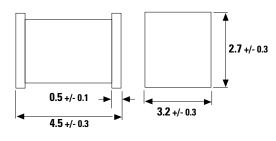
Soldering Parameters - Reflow Soldering (Surface Mount Devices)

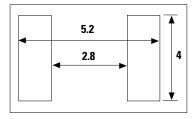
Reflow Condition		
-Temperature Min (T _{s(min)})	150°C	
-Temperature Max (T _{s(max)})	200°C	
-Time (Min to Max) (t _s)	60 – 180 secs	
Average ramp up rate (Liquidus Temp (T _L) to peak		
T _{S(max)} to T _L - Ramp-up Rate		
-Temperature (T _L) (Liquidus)	217°C	
-Temperature (t _L)	60 – 150 seconds	
Peak Temperature (T _p)		
Time within 5°C of actual peak Temperature (tp)		
Ramp-down Rate		
Time 25°C to peak Temperature (T _p)		
Do not exceed		
1	Temperature Min (T _{s(min)}) Temperature Max (T _{s(max)}) Time (Min to Max) (t _s) up rate (Liquidus Temp (T _L) to peak amp-up Rate Temperature (T _L) (Liquidus) Temperature (t _L) ture (T _p) C of actual peak Temperature (t _p)	



Device Dimensions

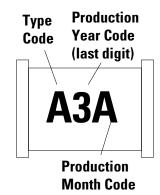
Dimensions in Millimeters.





Recommended Soldering Pad Layout

Device Marking



Type Code			
Α	SG75		
В	SG90		
С	SG150		
D	SG230		
E	SG300		
F	SG300Q		
G	SG350		
Н	SG350Q		
I	SG400		
J	SG420		
K	SG420Q		
L	SG450Q		
M	SG500Q		
N	SG600Q		
0	SG200		

Month Code			
Α	January		
В	February		
С	March		
D	April		
E	May		
F	June		
G	July		
Н	August		
ı	September		
J	October		
K	November		
L	December		